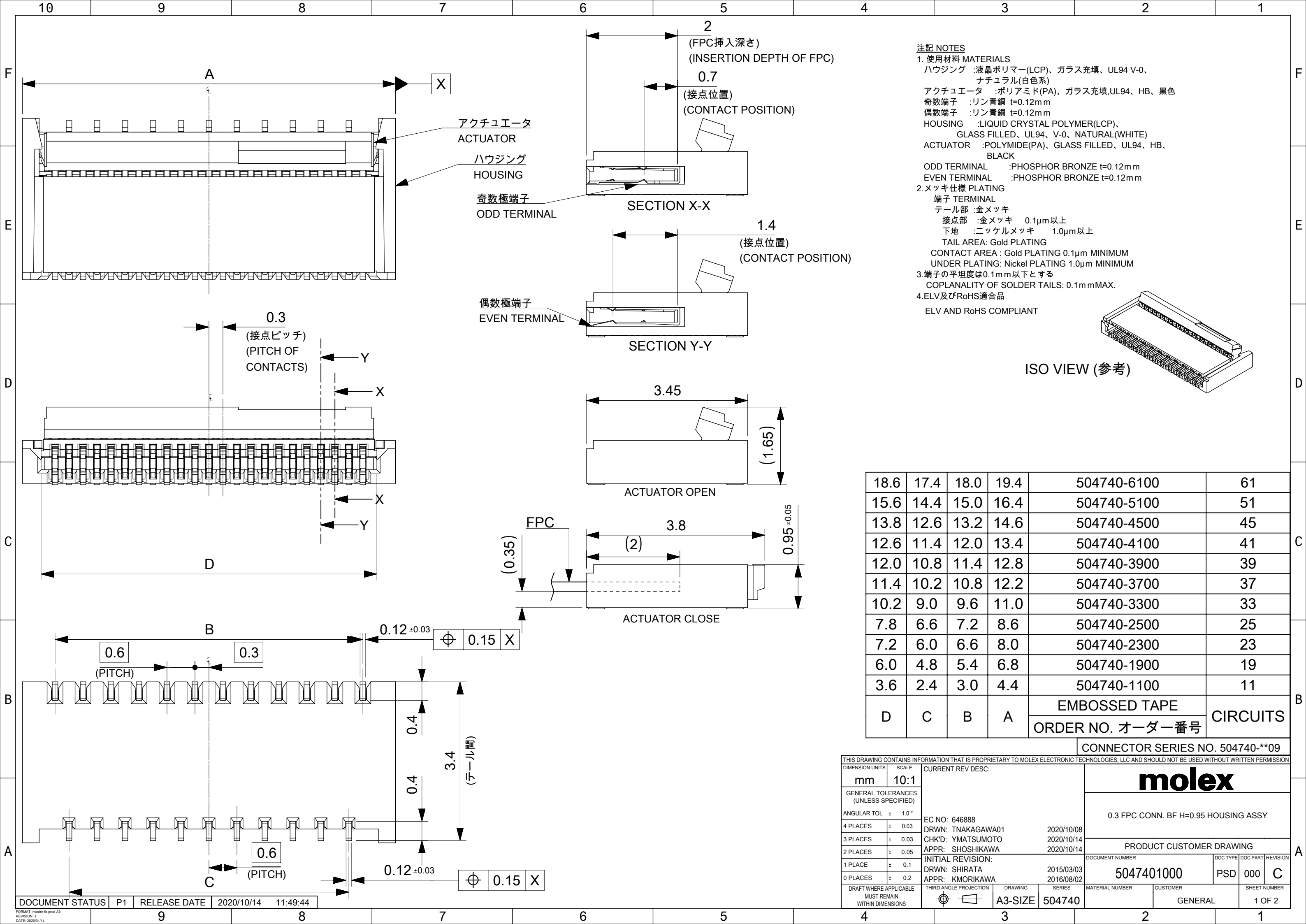




注記 NOTES

1. 使用材料 MATERIALS

ハウジング :液晶ポリマー(LCP)、ガラス充填、UL94 V-0、
ナチュラル(白色系)

アクチュエータ :ポリアミド(PA)、ガラス充填、UL94、HB、黒色

奇数端子 :リン青銅 t=0.12mm

偶数端子 :リン青銅 t=0.12mm

HOUSING :LIQUID CRYSTAL POLYMER(LCP)、
GLASS FILLED、UL94、V-0、NATURAL(WHITE)

ACTUATOR :POLYIMIDE(PA)、GLASS FILLED、UL94、HB、
BLACK

ODD TERMINAL :PHOSPHOR BRONZE t=0.12mm

EVEN TERMINAL :PHOSPHOR BRONZE t=0.12mm

2. メッキ仕様 PLATING

端子 TERMINAL

テール部 :金メッキ

接点部 :金メッキ 0.1μm以上

下地 :ニッケルメッキ 1.0μm以上

TAIL AREA: Gold PLATING

CONTACT AREA : Gold PLATING 0.1μm MINIMUM

UNDER PLATING: Nickel PLATING 1.0μm MINIMUM

3. 端子の平坦度は0.1mm以下とする

COPLANALITY OF SOLDER TAILS: 0.1mm MAX.

4. ELV及びRoHS適合品

ELV AND RoHS COMPLIANT

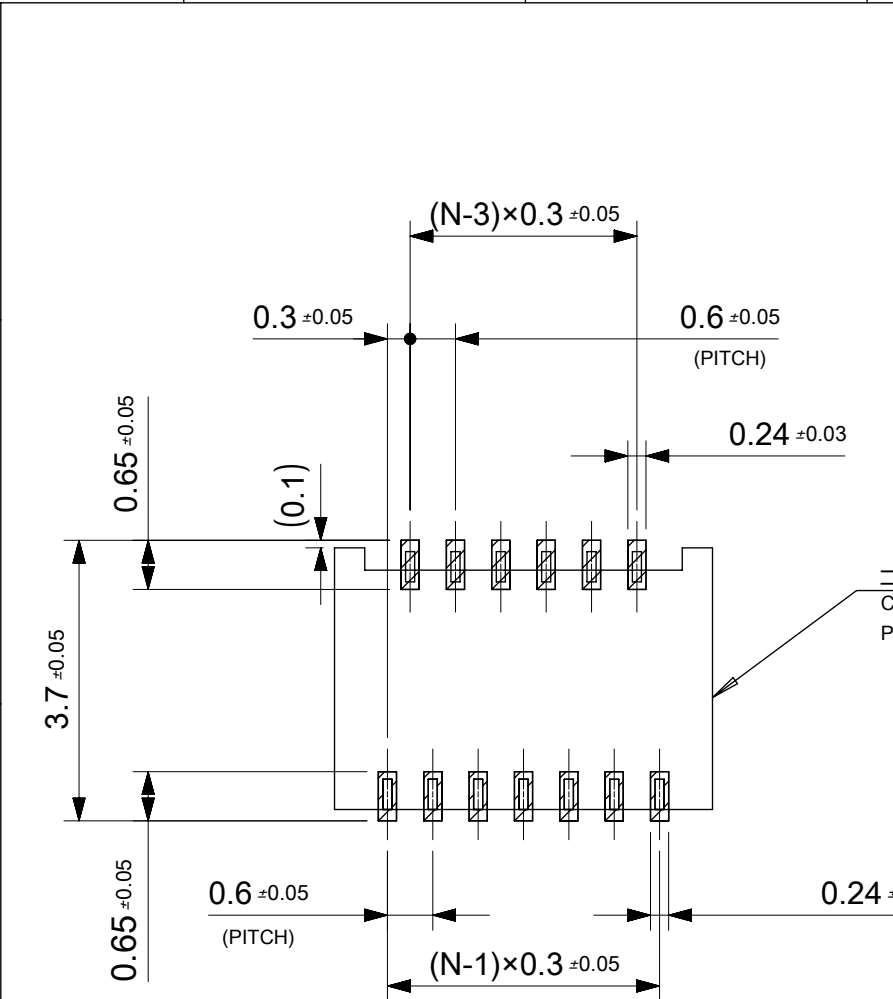
18.6	17.4	18.0	19.4	504740-6100	61
15.6	14.4	15.0	16.4	504740-5100	51
13.8	12.6	13.2	14.6	504740-4500	45
12.6	11.4	12.0	13.4	504740-4100	41
12.0	10.8	11.4	12.8	504740-3900	39
11.4	10.2	10.8	12.2	504740-3700	37
10.2	9.0	9.6	11.0	504740-3300	33
7.8	6.6	7.2	8.6	504740-2500	25
7.2	6.0	6.6	8.0	504740-2300	23
6.0	4.8	5.4	6.8	504740-1900	19
3.6	2.4	3.0	4.4	504740-1100	11
D	C	B	A	EMBOSSED TAPE	CIRCUITS
ORDER NO. オーダー番号					

CONNECTOR SERIES NO. 504740-**09

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													
DIMENSION UNITS		SCALE		CURRENT REV DESC:			molex						
mm		10:1											
GENERAL TOLERANCES (UNLESS SPECIFIED)													
ANGULAR TOL		± 1.0 °		0.3 FPC CONN. BF H=0.95 HOUSING ASSY									
4 PLACES		± 0.03		EC NO: 646888			PRODUCT CUSTOMER DRAWING						
3 PLACES		± 0.03		DRWN: TNAKAGAWA01 2020/10/08									
2 PLACES		± 0.05		CHK'D: YMATSUMOTO 2020/10/14									
1 PLACE		± 0.1		APPR: SHOSHIKAWA 2020/10/14			DOCUMENT NUMBER						
0 PLACES		± 0.2		INITIAL REVISION:						5047401000			
DRWN: SHIRATA 2015/03/03				DOC TYPE			DOC PART		REVISION				
APPR: KMORIKAWA 2016/08/02				PSD			000		C				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING	SERIES	MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
						A3-SIZE	504740			GENERAL		1 OF 2	

DOCUMENT STATUS	P1	RELEASE DATE	2020/10/14	11:49:44
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FORMAT: master-B-prod-A3
REVISION: J
DATE: 2020/01/14



参照基板レイアウト(マウント面)

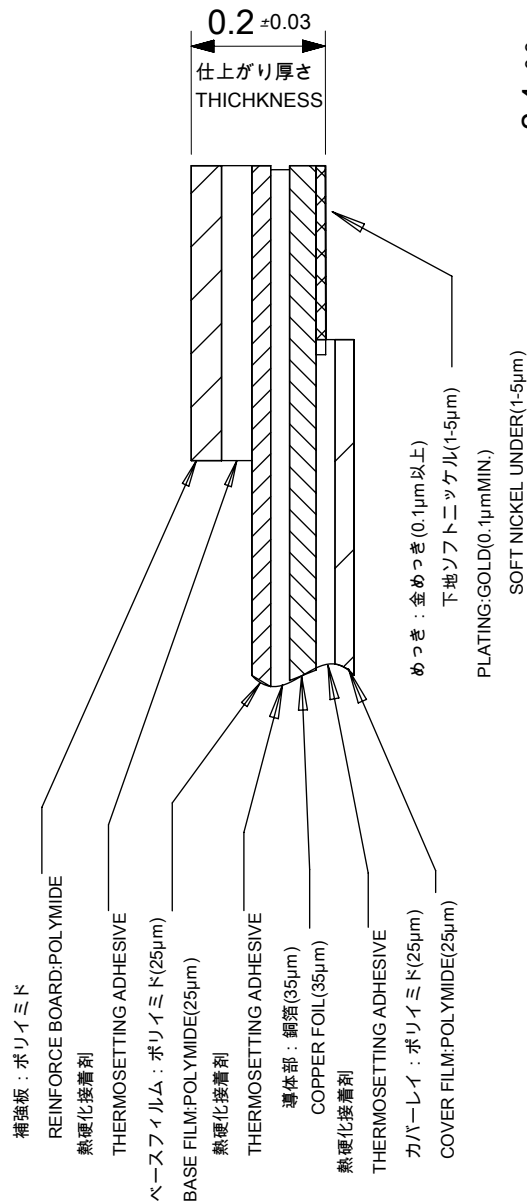
P.W.BOARD PATTERN

DIM.(REF)

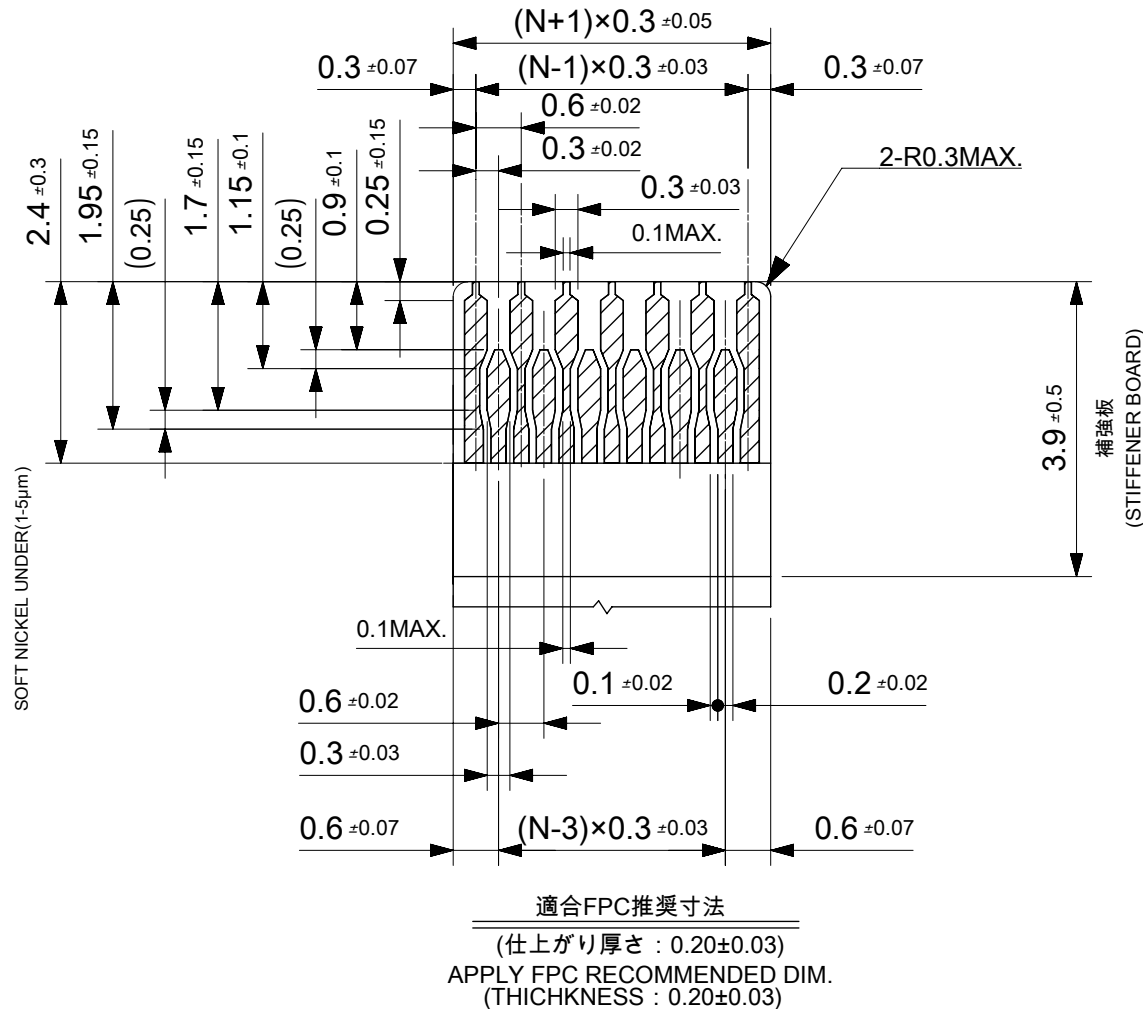
推奨メタルマスク厚さ : 0.1mm

RECOMMENDED METAL MASK THICKNESS : 0.1mm

推奨開口率 : 80%
APERTURE RATE : 80%

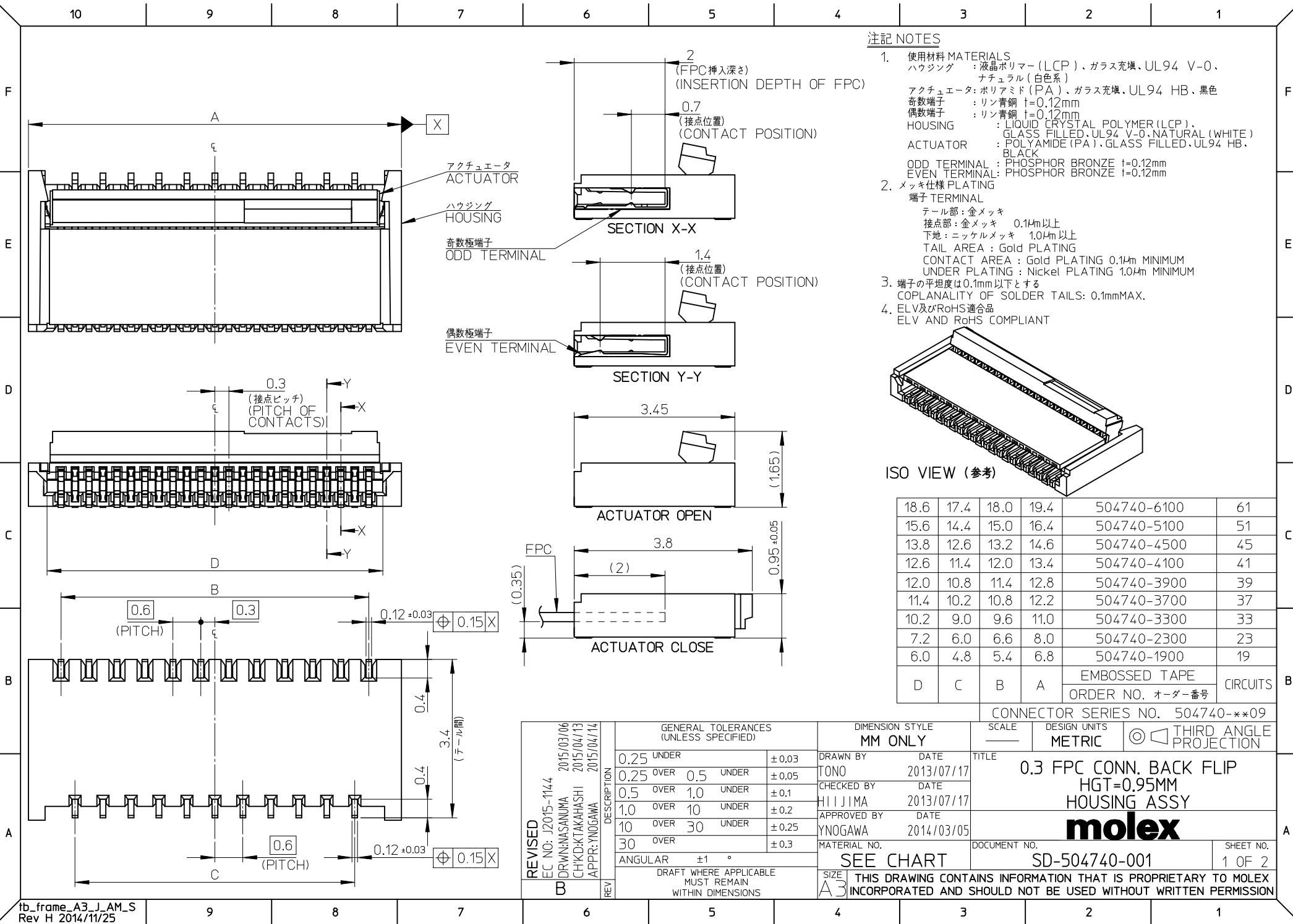


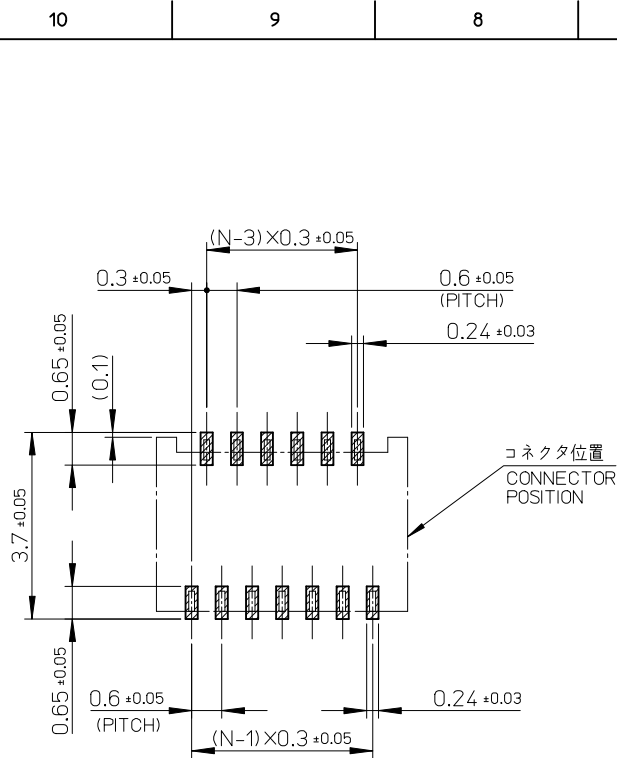
FPC構成推奨仕様
STRUCTURE OF FPC



FPCについて (ABOUT FPC)
抜き方向は、導体側から補強版側を推奨致します。
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。
WHEN STIFFNER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFNER BOARD AS 0.5mm MINIMUM.





参照基板レイアウト(マウント面)

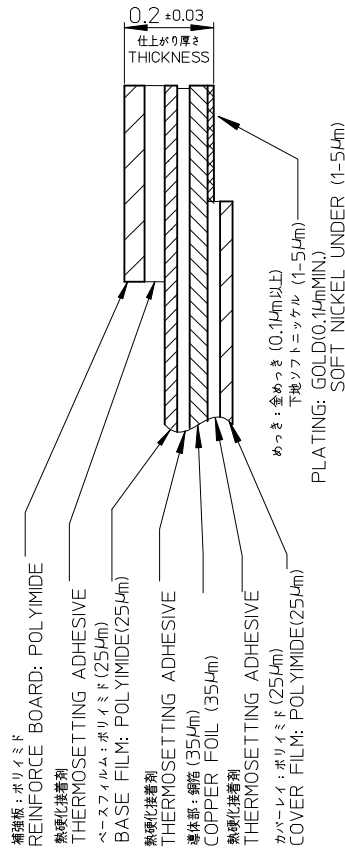
P.W. BOARD PATTERN
DIM.(REF)

推奨メタルマスク厚さ : 0.1mm

RECOMMENDED METAL MASK THICKNESS : 0.1mm

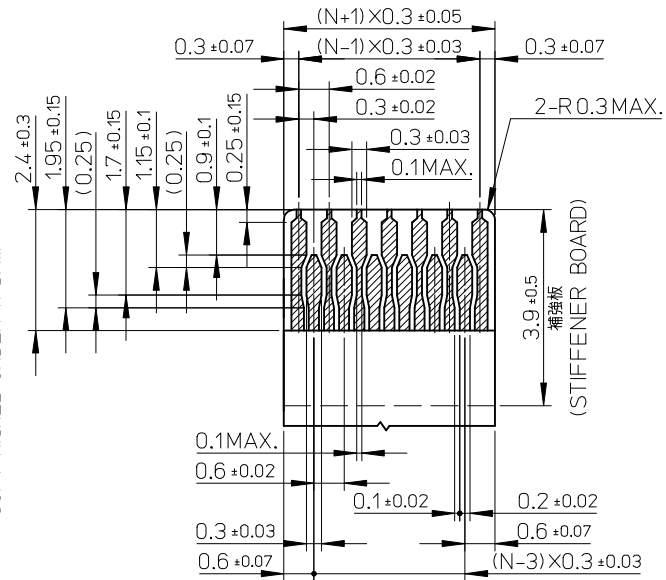
推奨開口率 : 80%

APERTURE RATE : 80%



FPC構成推奨仕様

STRUCTURE OF FPC



適合FPC推奨寸法

(仕上がり厚さ : 0.20±0.03)

APPLY FPC RECOMMENDED DIM.

(THICKNESS : 0.20±0.03)

FPCについて (ABOUT FPC)

抜き方向は、導体側から補強版側を推奨致します。

補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。

尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

RECOMMENDED PUNCHER DIRECTION:

FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

RECOMMENDED MATERIAL:

STIFFENER BOARD: POLYIMIDE

BONDING AGENT: THERMOSETTING AGENT

PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND

BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

※1 補強板の長さが図面通りに確保できない場合は、カバーレイと

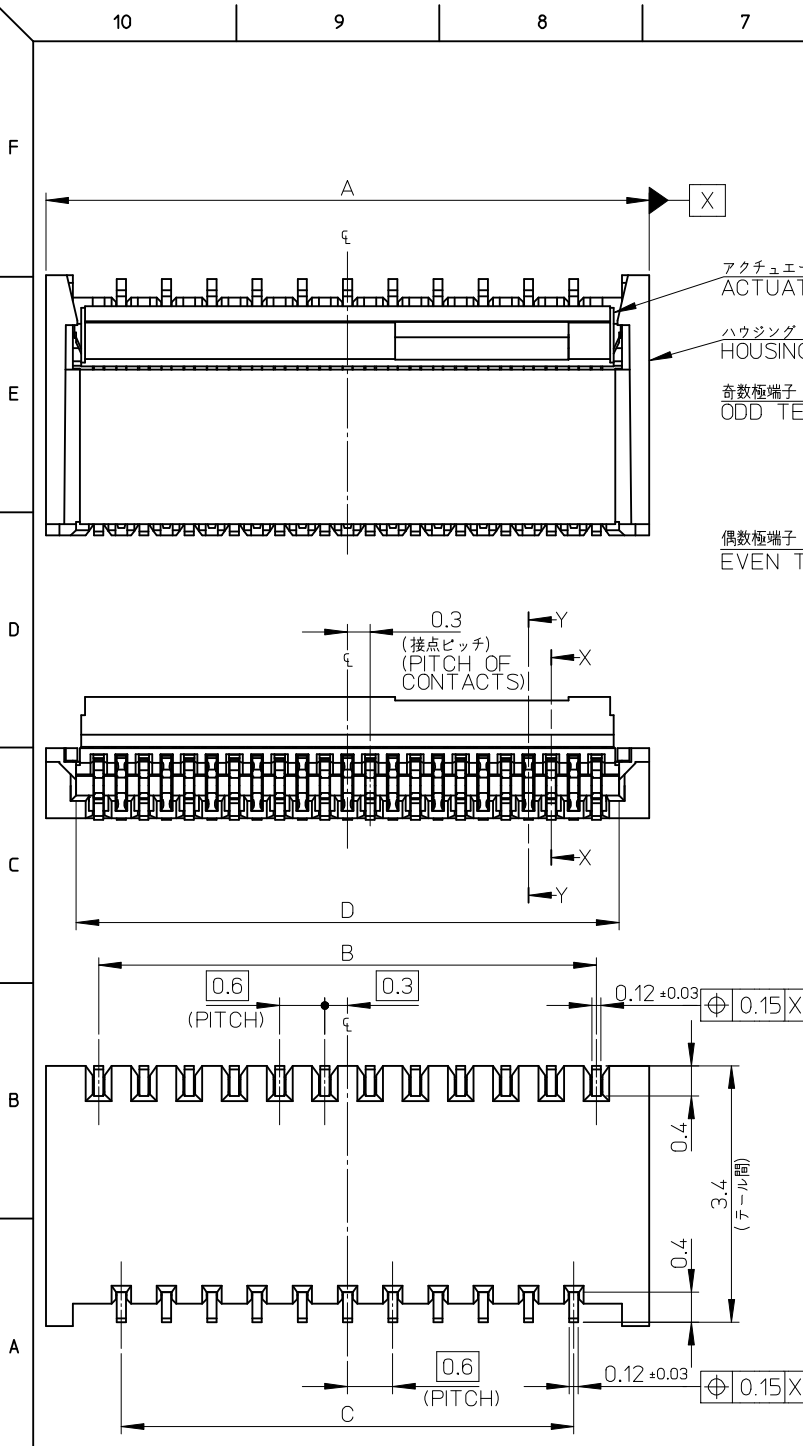
補強板のオーバーラップ寸法を0.5mm以上としてください。

WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE

AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF

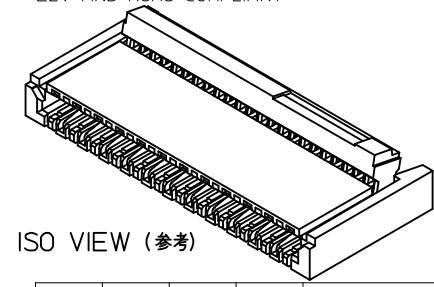
COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM.

SEE SHEET 1 OF 2	EC NO: J2015-1144	DRAWN: SANJUMA 2015/03/06 CHK: K. TAKAHASHI 2015/04/13 APPR: YNOGAWA 2015/04/14	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				0.25 UNDER	± 0.03	DRAWN BY	DATE	TITLE 0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY				
				0.25 OVER 0.5 UNDER	± 0.05	TONO	2013/07/17					
				0.5 OVER 1.0 UNDER	± 0.1	CHECKED BY	DATE	DOCUMENT NO. SD-504740-001				
				1.0 OVER 10 UNDER	± 0.2	HIJIMA	2013/07/17					
				10 OVER 30 UNDER	± 0.25	APPROVED BY	DATE	SHEET NO. 2 OF 2				
				30 OVER	± 0.3	YNOGAWA	2014/03/05					
				ANGULAR ±1 °		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1 OF 2						
				REV			SIZE A3					



注記 NOTES

- 使用材料 MATERIALS
ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94 V-0、
ナチュラル (白色系)
アクチュエータ: ポリアミド (PA)、ガラス充填、UL94 HB、黒色
奇数端子 : リン青銅 $t=0.12\text{mm}$
偶数端子 : リン青銅 $t=0.12\text{mm}$
HOUSING : LIQUID CRYSTAL POLYMER (LCP)、
GLASS FILLED、UL94 V-0、NATURAL (WHITE)
ACTUATOR : POLYAMIDE (PA)、GLASS FILLED、UL94 HB、
BLACK
ODD TERMINAL : PHOSPHOR BRONZE $t=0.12\text{mm}$
EVEN TERMINAL : PHOSPHOR BRONZE $t=0.12\text{mm}$
- メッキ仕様 PLATING
端子 TERMINAL
テール部: 金メッキ
接点部: 金メッキ 0.1 μm 以上
下地: ニッケルメッキ 1.0 μm 以上
TAIL AREA : Gold PLATING
CONTACT AREA : Gold PLATING 0.1 μm MINIMUM
UNDER PLATING : Nickel PLATING 1.0 μm MINIMUM
- 端子の平坦度は0.1mm以下とする
COPLANALITY OF SOLDER TAILS: 0.1mm MAX.
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

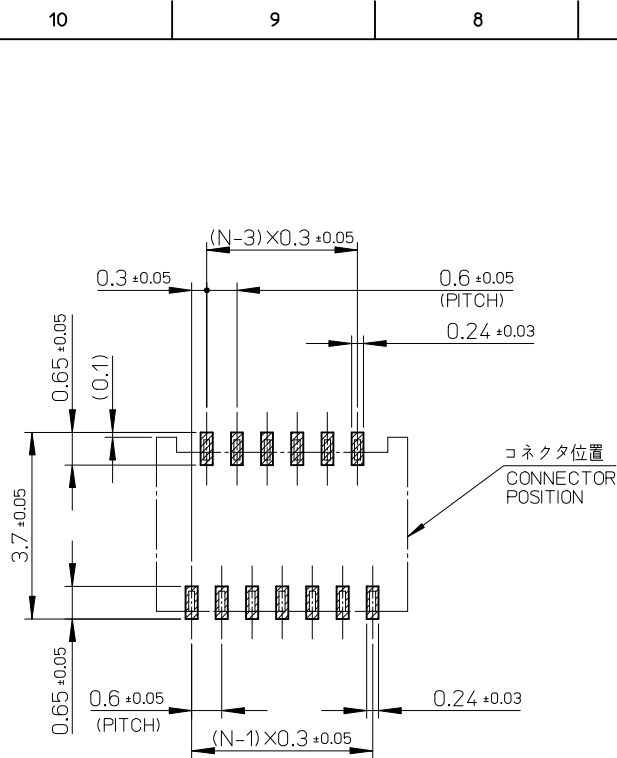


ISO VIEW (参考)

18.6	17.4	18.0	19.4	504740-6100	61
15.6	14.4	15.0	16.4	504740-5100	51
13.8	12.6	13.2	14.6	504740-4500	45
12.6	11.4	12.0	13.4	504740-4100	41
12.0	10.8	11.4	12.8	504740-3900	39
11.4	10.2	10.8	12.2	504740-3700	37
10.2	9.0	9.6	11.0	504740-3300	33
7.2	6.0	6.6	8.0	504740-2300	23
6.0	4.8	5.4	6.8	504740-1900	19
D	C	B	A	EMBOSSED TAPE	CIRCUITS
				ORDER NO. オーダー番号	

CONNECTOR SERIES NO. 504740-**09

REVISED EC NO: J2015-1144 DRAWN: NAKANUMA 2015/03/06 CHKD: KATAKASHI 2015/04/13 APPR: YNOGAWA 2015/04/14	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		0.25 UNDER		± 0.03	DRAWN BY	DATE	TITLE 0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY molex	DOCUMENT NO. SD-504740-001	SHEET NO. 1 OF 2	
		0.25 OVER 0.5 UNDER		± 0.05	TONO	2013/07/17				
		0.5 OVER 1.0 UNDER		± 0.1	CHECKED BY	DATE				
		1.0 OVER 10 UNDER		± 0.2	HIJIMA	2013/07/17				
		10 OVER 30 UNDER		± 0.25	APPROVED BY	DATE				
		30 OVER		± 0.3	YNOGAWA	2014/03/05				
		ANGULAR ±1 °			MATERIAL NO.					
					SEE CHART					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



参照基板レイアウト(マウント面)

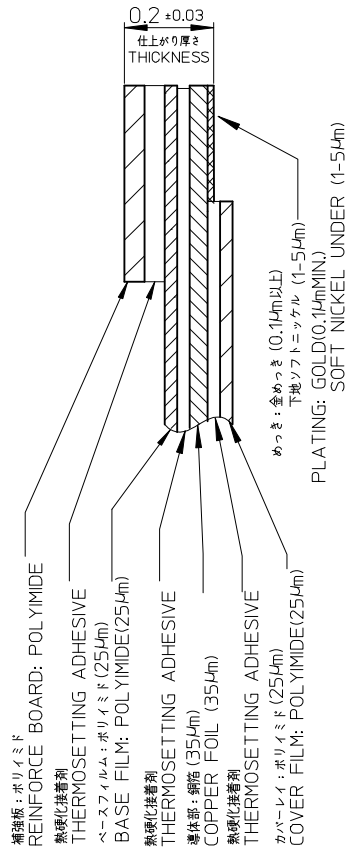
P.W. BOARD PATTERN
DIM.(REF)

推奨メタルマスク厚さ : 0.1mm

RECOMMENDED METAL MASK THICKNESS : 0.1mm

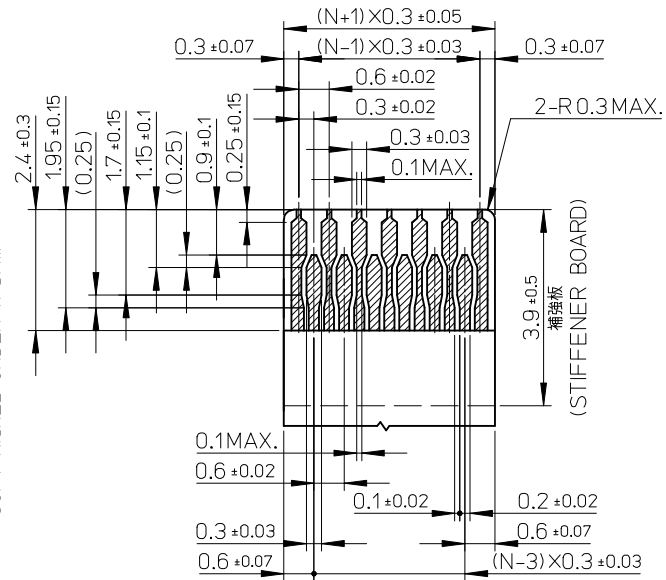
推奨開口率 : 80%

APERTURE RATE : 80%



FPC構成推奨仕様

STRUCTURE OF FPC



適合FPC推奨寸法

(仕上がり厚さ : 0.20±0.03)

APPLY FPC RECOMMENDED DIM.

(THICKNESS : 0.20±0.03)

FPCについて (ABOUT FPC)

抜き方向は、導体側から補強版側を推奨致します。

補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。

尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

RECOMMENDED PUNCHER DIRECTION:

FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

RECOMMENDED MATERIAL:

STIFFENER BOARD: POLYIMIDE

BONDING AGENT: THERMOSETTING AGENT

PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND

BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

※1 補強板の長さが図面通りに確保できない場合は、カバーレイと

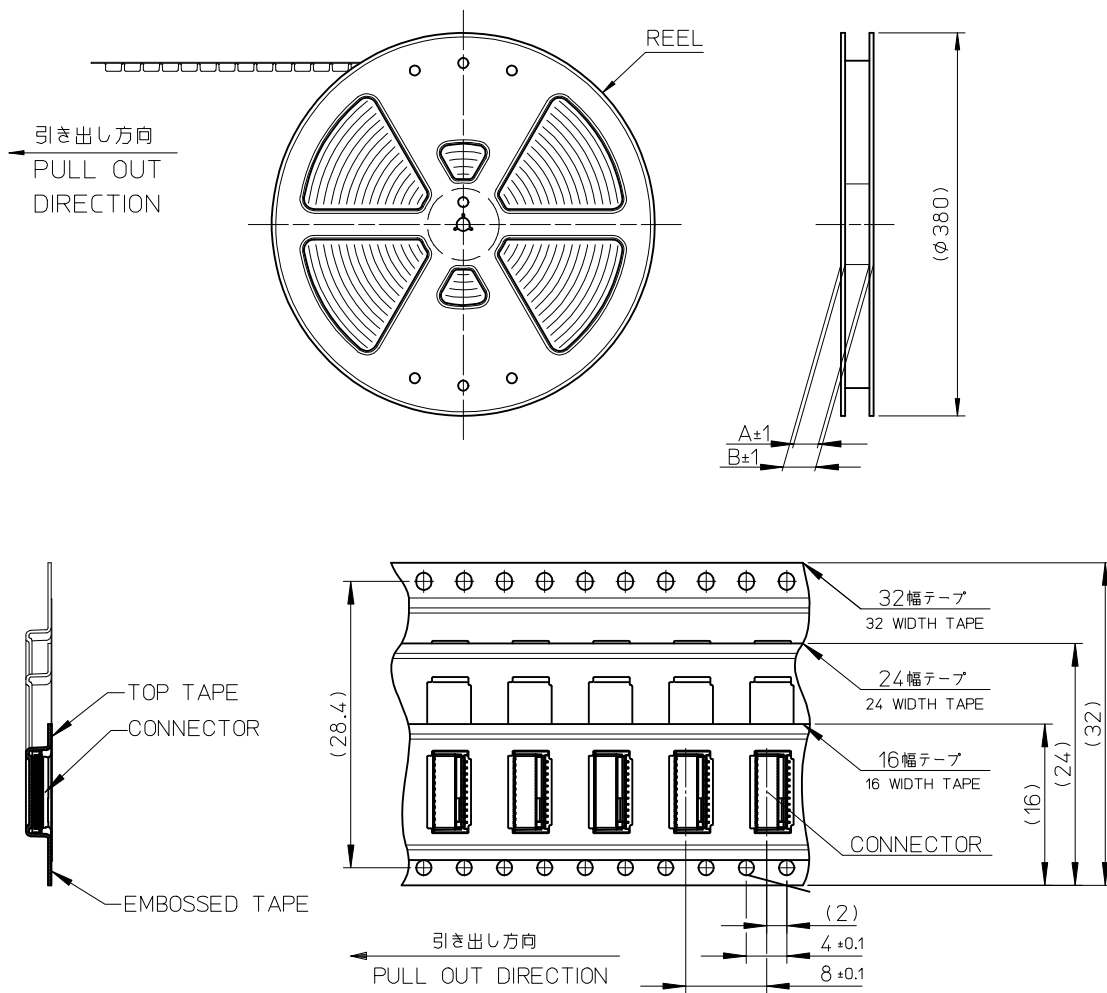
補強板のオーバーラップ寸法を0.5mm以上としてください。

WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE

AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF

COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM.

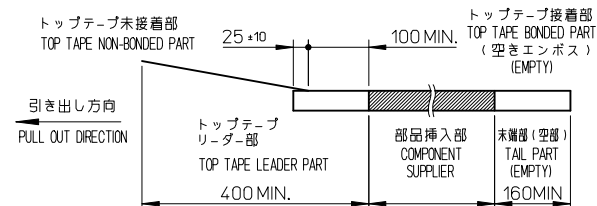
SEE SHEET 1 OF 2	EC NO: J2015-1144	DRAWN: SANJUMA 2015/03/06 CHKD: KATAHASHI 2015/04/13 APPR: YNOGAWA 2015/04/14	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE _____	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION 			
				0.25 UNDER		± 0.03	DRAWN BY	DATE	TITLE 0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY					
				0.25 OVER 0.5 UNDER	± 0.05	TONO	2013/07/17							
				0.5 OVER 1.0 UNDER		± 0.1	CHECKED BY	DATE	DOCUMENT NO. SD-504740-001					
				1.0 OVER 10 UNDER	± 0.2	HIJIMA	2013/07/17							
				10 OVER 30 UNDER		± 0.25	APPROVED BY	DATE	SHEET NO. 2 OF 2					
				30 OVER	± 0.3	YNOGAWA	2014/03/05							
				ANGULAR ±1 °			MATERIAL NO.			SEE SHEET 1 OF 2				
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



エンボステープ内の製品の向き
DIRECTION OF CONNECTOR IN
EMBOSSED TAPE

NOTES

- 製品詳細寸法については、図面 SD-504740-001をご参照下さい。
REFER TO THE SD-504740-001 ABOUT DIMENSIONS IN DETAIL.
- 梱包数量 : 5000 個/リール
NUMBER OF CONNECTORS : 5000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度については、IEC60286-3 に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.
- 材料
キャリアテープ : ポリスチレン (PS)
トップテープ : PET, OTHER
リール : ポリスチレン (PS) <リサイクル材を含む>
MATERIAL
CARRIER TAPE : POLYSTYRENE(PS)
TOP TAPE : PET, OTHER
REEL : POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>

32	37.4	33.4	504740-6100	61
			504740-5100	51
			504740-4500	45
			504740-4100	41
24	29.4	25.4	504740-3900	39
			504740-3700	37
			504740-3300	33
16	21.4	17.4	504740-2300	23
			504740-1900	19
テープ幅 TAPE WIDTH	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUIT
CONDUCTOR SERIES NO.			504740-**09	

REVISED EC NO.: J2015-1144 DRAWN: SANUMA CHK'D: TAKAHASHI APPR: YNOGAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 1:0	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION							
		0.25 UNDER	UNDER	± 0.03	DRAWN BY	DATE	TITLE 0.3 FPC CONN. BACK FLIP HGT=0.95MM EMBSTP PKG molex									
		0.25 OVER	0.5 UNDER	± 0.05	TONO	2013/07/25										
		0.5 OVER	1.0 UNDER	± 0.1	CHECKED BY	DATE										
		1.0 OVER	10 UNDER	± 0.2	HIJIMA	2013/07/25										
		10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE	DOCUMENT NO. SD-504740-002									
		30 OVER		± 0.3	YNOGAWA	2014/03/05										
		ANGULAR ±1 °			MATERIAL NO.		SHEET NO. 1 OF 1									
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3							THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
B	REV															